CLAIMS

1. A process for producing a semiconductor package having a semiconductor element and a resin sealed portion formed from a curable resin for sealing the semiconductor element, characterized by comprising

a step of disposing a mold release film on a surface of a mold which is to be in contact with a curable resin,

the mold release film being formed by:

a process for producing a semiconductor package by disposing a semiconductor element in the mold, and sealing it with the curable resin to form a resin sealed portion, characterized by comprising a first thermoplastic resin layer to be in contact with the curable resin at the time of forming the resin sealed portion, a second thermoplastic resin layer to be in contact with the mold at the time of forming the resin sealed portion, and an interlayer disposed between the first thermoplastic resin layer and the second thermoplastic resin layer, wherein the first thermoplastic resin layer and the second thermoplastic resin layer have a storage elastic modulus at 180°C of from 10 to 300 MPa, respectively, the difference in storage elastic modulus at 25°C between them is at most 1,200 MPa, and their thicknesses are from 12 to 50 μm, and the interlayer includes a layer containing a polymeric antistatic agent;

a step of disposing a substrate having a semiconductor element mounted thereon, in the mold, and filling a curable resin in a space in the mold, followed by curing to form a resin sealed portion, thereby to obtain a sealed body having the substrate, the semiconductor element and the resin sealed portion; and

a step of releasing the sealed body from the mold,

wherein in the step of obtaining a sealed body, a part of the semiconductor element is in direct contact with said release film.